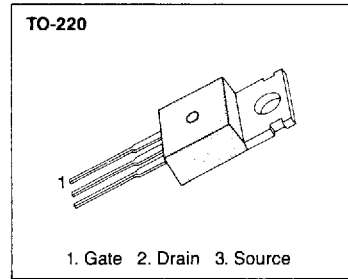


## FEATURES

- Lower  $R_{DS(on)}$
- Improved inductive ruggedness
- Fast switching times
- Rugged polysilicon gate cell structure
- Lower input capacitance
- Extended safe operating area
- Improved high temperature reliability



## PRODUCT SUMMARY

Part Number	V <sub>DS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
IRFZ34	60V	0.05Ω	30A
IRFZ30	50V	0.05Ω	30A

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## ABSOLUTE MAXIMUM RATINGS

Characteristic	Symbol	IRFZ34	IRFZ30	Unit
Drain-Source Voltage (1)	V <sub>DS</sub>	60	50	V <sub>dc</sub>
Drain-Gate Voltage (R <sub>GS</sub> =1.0MΩ)(1)	V <sub>DGR</sub>	60	50	V <sub>dc</sub>
Gate-Source Voltage	V <sub>GS</sub>	±20		V <sub>dc</sub>
Continuous Drain Current T <sub>C</sub> =25 °C	I <sub>D</sub>	30		A <sub>dc</sub>
Continuous Drain Current T <sub>C</sub> =100 °C	I <sub>D</sub>	21		A <sub>dc</sub>
Drain Current - Pulsed (3)	I <sub>DM</sub>	120		A <sub>dc</sub>
Gate Current - Pulsed	I <sub>GM</sub>	±1.5		A <sub>dc</sub>
Single Pulsed Avalanche Energy (4)	E <sub>AS</sub>	19		mJ
Avalanche Current	I <sub>AS</sub>	30		A
Total Power Dissipation at T <sub>C</sub> =25 °C	P <sub>D</sub>	90		Watts
Derate above 25 °C		0.60		W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175		°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	T <sub>L</sub>	300		°C

Notes : (1) T<sub>J</sub>=25°C to 175°C

(2) Pulse test : Pulse width < 300μs, Duty Cycle ≤ 2%

(3) Repetitive rating : Pulse width limited by max. junction temperature

(4) L=50μH, V<sub>DD</sub>=25V, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C

## ELECTRICAL CHARACTERISTICS (T<sub>c</sub>=25°C unless otherwise specified)

Symbol	Characteristic	Min	Typ	Max	Units	Test Conditions
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage					
	IRFZ34	60	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA
	IRFZ30	50	-	-	V	
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0	-	4.0	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
I <sub>GSS</sub>	Gate-Source Leakage Forward	-	-	100	nA	V <sub>GS</sub> =20V
I <sub>GSS</sub>	Gate-Source Leakage Reverse	-	-	-100	nA	V <sub>GS</sub> =-20V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	-	-	250	μA	V <sub>DS</sub> =Max. Rating, V <sub>GS</sub> =0V
		-	-	1000	μA	V <sub>DS</sub> =0.8 Max. Rating, V <sub>GS</sub> =0V, T <sub>c</sub> =150°C
R <sub>DS(on)</sub>	Static Drain-Source On Resistance(2)	-	-	0.05	Ω	V <sub>GS</sub> =10V, I <sub>D</sub> =15A
g <sub>fs</sub>	Forward Transconductance (2)	9.3	-	-	Ω	V <sub>DS</sub> ≥ 50V, I <sub>D</sub> =15A
C <sub>iss</sub>	Input Capacitance	-	1300	-	pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1.0MHz
C <sub>oss</sub>	Output Capacitance	-	650	-	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance	-	100	-	pF	
t <sub>d(on)</sub>	Turn-On Delay Time	-	-	21	ns	V <sub>DD</sub> =0.5 BV <sub>DSS</sub> , I <sub>D</sub> =30A, Z <sub>Θ</sub> =18Ω (MOSFET switching times are essentially independent of operating temperature)
t <sub>r</sub>	Rise Time	-	-	110	ns	
t <sub>d(off)</sub>	Turn-Off Delay Time	-	-	53	ns	
t <sub>f</sub>	Fall Time	-	-	80	ns	
Q <sub>g</sub>	Total Gate Charge (Gate-Source Plus Gate-Drain)	-	-	49.0	nC	V <sub>GS</sub> =10V, I <sub>D</sub> =30A, V <sub>DS</sub> =0.8 Max. Rating (Gate charge is essentially independent of operating temperature)
Q <sub>gs</sub>	Gate-Source Charge	-	14.3	-	nC	
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	-	16.3	-	nC	

## THERMAL RESISTANCE

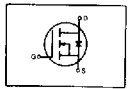
Symbol	Characteristics		All	Units	Remark
R <sub>thJC</sub>	Junction-to-Case	MAX	1.67	K/W	
R <sub>thCS</sub>	Case-to-Sink	TYP	0.5	K/W	Mounting surface flat
R <sub>thJA</sub>	Junction-to-Ambient	MAX	62.5	K/W	Free Air Operation

Notes : (1) T<sub>J</sub>=25°C to 175°C

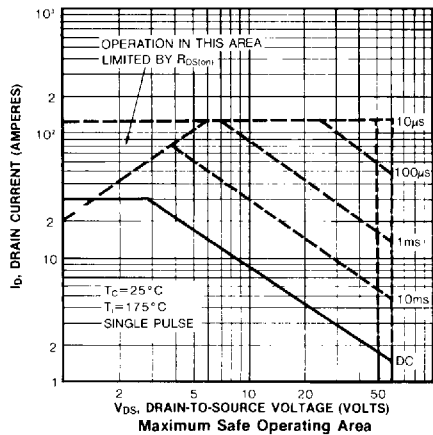
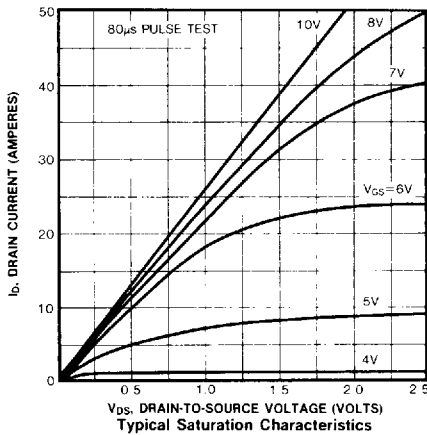
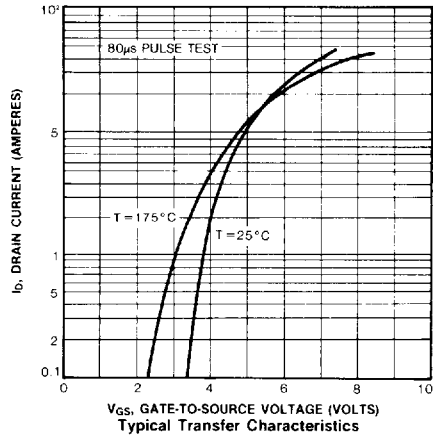
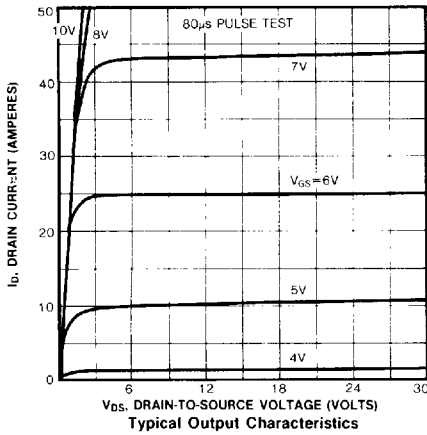
(2) Pulse test : Pulse width ≤ 300μs, Duty Cycle ≤ 2%

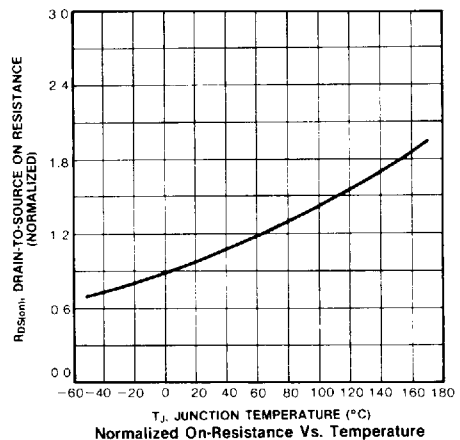
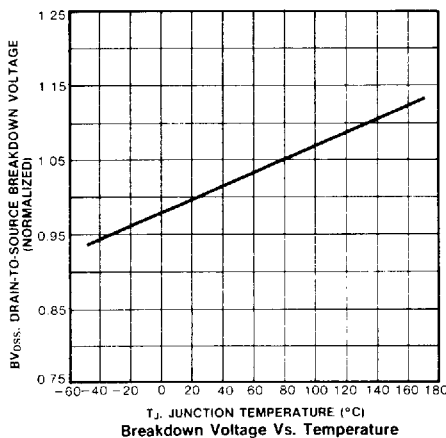
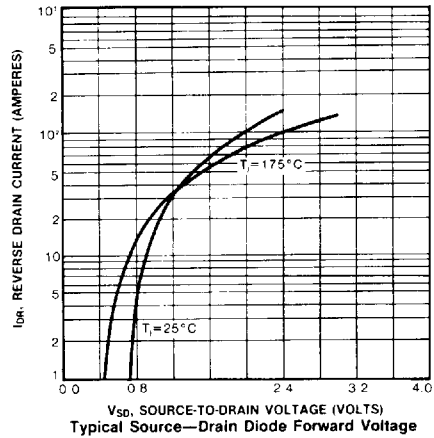
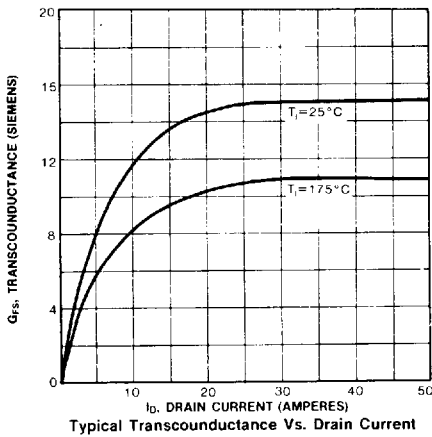
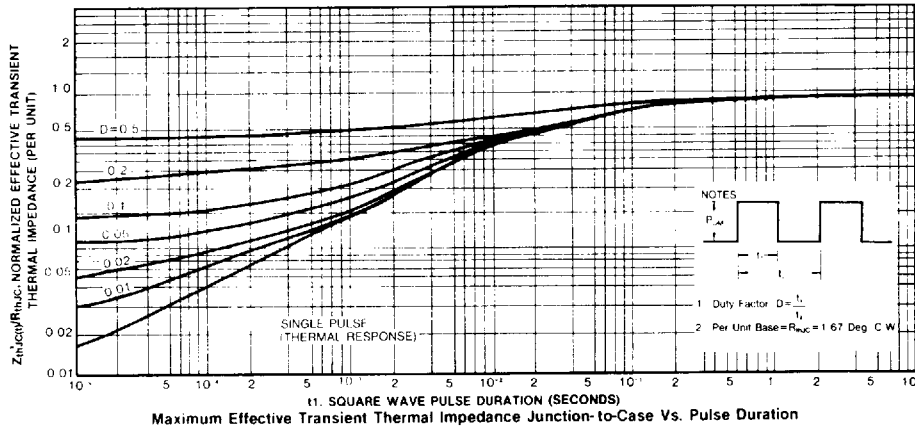
(3) Repetitive rating : Pulse width limited by max. junction temperature

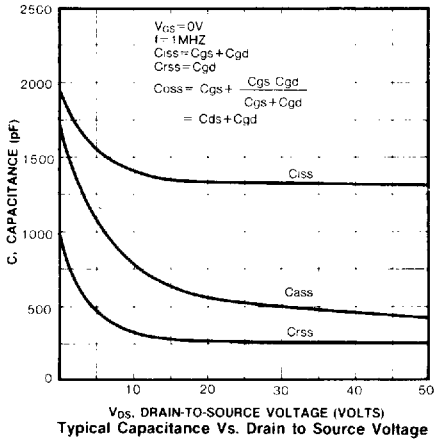
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic	Min	Typ	Max	Units	Test Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	-	-	30	A	Modified MOSFET symbol showing the integral reverse P-N junction rectifier 
I <sub>SM</sub>	Pulse Source Current (Body Diode) (3)	-	-	120	A	
V <sub>SD</sub>	Diode Forward Voltage (2)	-	-	1.6	V	T <sub>J</sub> =25°C, I <sub>S</sub> =30A, V <sub>GS</sub> =0V
t <sub>rr</sub>	Reverse Recovery Time	-	-	220	ns	T <sub>J</sub> =25°C, I <sub>F</sub> =30A, dI <sub>F</sub> /dt=100A/μS

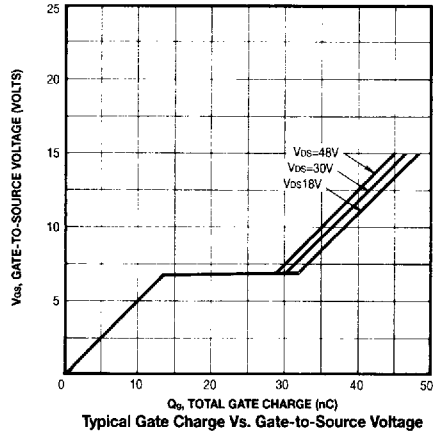
- Notes : (1) T<sub>J</sub>=25°C to 175°C  
 (2) Pulse test : Pulse width ≤ 300μs, Duty Cycle ≤ 2%  
 (3) Repetitive rating : Pulse width limited by max. junction temperature



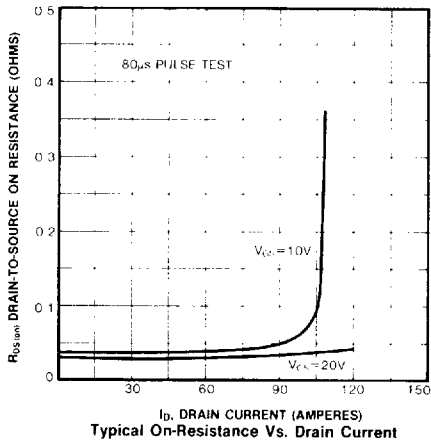




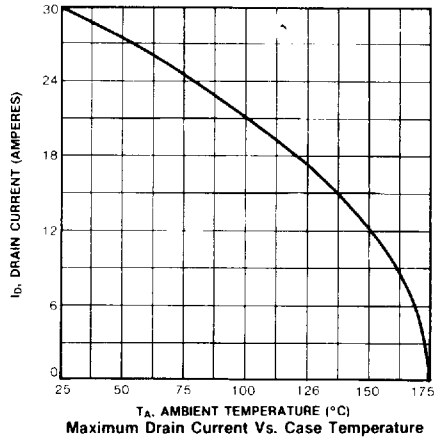
Typical Capacitance Vs. Drain to Source Voltage



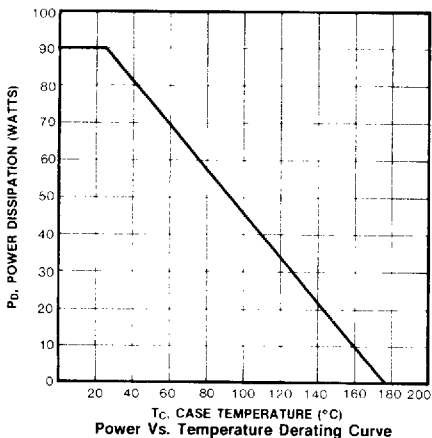
Typical Gate Charge Vs. Gate-to-Source Voltage



Typical On-Resistance Vs. Drain Current



Maximum Drain Current Vs. Case Temperature



Power Vs. Temperature Derating Curve

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